



162162

ABSTRACT



G00002

Method and Apparatus for dispensing solder

5

This invention relates to a method for dispensing solder into contact with a substrate to be soldered wherein the part of the dispensing pathway that comes into contact
10 with liquid solder is lined with a material suitable for assuaging the clogging of said pathway.

In one embodiment, the lining is provided in the form of a removable insert (30) lining the solder dispensing
15 pathway (26) of the dispenser tool or tip (20). Upon being worn out the insert (30) may be replaced with a new one, without the need for replacing the entire dispenser tool (20).

20 In another embodiment, the reinforcement is provided in the form of a coating (50) lining the solder dispensing pathway of the dispenser tool (20).

25

FIGUREs 2